**Product End-of-Life Disassembly Instructions**

**Product Category:** Monitors and Displays

**Marketing Name / Model**
[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>Name / Model #1</th>
<th>HP LE1911 LCD Monitor</th>
</tr>
</thead>
<tbody>
<tr>
<td>Name / Model #2</td>
<td></td>
</tr>
<tr>
<td>Name / Model #3</td>
<td></td>
</tr>
<tr>
<td>Name / Model #4</td>
<td></td>
</tr>
<tr>
<td>Name / Model #5</td>
<td></td>
</tr>
</tbody>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>2</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>1</td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>SCREW DRIVER(PHILLIPS HEAD) #2</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. External Electric Cables Dissecting Process
2. Remove Stand Base From Display
3. Remove Front Cover From Display Head
4. Remove Rear Cover From Display Head
5. Remove Mainframe &Panel
6. Take Screw off From Power Bd & Main Bd & Remove Mainframe
7. Remove Stand Cover From Stand&Base
8. Remove Base Cover From Stand&Base

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
HP- LE1x11 Disassembly Process

Kevin Lin
Jul-20-09
1. Remove Cable From Display Head.

2. Dissecting To Complete.

Power Cable
Remove Stand Base From Display

1. Take Screw(*3) From Stand & Remove Stand Base From Display.

2. Take Screw(*4) From Rear Cover.

3. Take Screw(*4) From hanging.
Remove Front & Rear Cover From Display Head


2. Toward the arrowhead, take the KEPC board from the Front Cover.

3. Remove Front Cover.
Remove Mainframe & Panel

1. Remove Connector off from KEPC board.

2. Take Screw(*2) From Mainframe.

3. Take Screw(*2) From Mainframe.

4. Remove the Conductive Tape from the Mainframe.
1. Toward the arrowhead, Remove the sheet iron from Mainframe.

2. Remove Connector off from Power board.

3. Remove connector off from Panel.

4. Remove the panel.
Take Screw off From Power Bd & Main Bd & Remove Mainframe

1. Remove Insulator Sheet off from Mainframe.

2. Remove the Conductive Tape from the Mainframe.
Take Screw off From Power Bd & Main Bd & Remove Mainframe

1. Take screw(*2) off from Mainboard.

2. Take screw(*1) off from Mainboard.

3. Take Mainboard off from Mainframe.

4. Remove Connector off from Mainboard.
Take Screw off From Power Bd & Main Bd & Remove Mainframe

1. Take screw(×5) off from Power board.

2. Take Power board off from Mainframe.

3. Dissecting to complete.
Remove Stand&Base Cover From Stand&Base

1. Press down the Stand, push up the Hinge Cover and remove it.

2. Take base switch

3. Pull off the bracket

4. Dissecting to complete.
1. Disassemble hinge cover

2. Take screw(*2) off from Rear Stand Cover.

3. Remove the Front Stand Cover.
Remove Stand&Base Cover From Stand&Base

1. Take screw(*) off from hinge

2. Dissecting To Complete.
1. Remove Base foot.

2. Take screw(*6) off, and remove Base Trim Cover.

3. Dissecting To Complete.

4. Dissecting To Complete.